Hewlett Packard
Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HPE Synergy D3940 Storage Module
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		6
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T15,T10
Phillips screw driver	PH1
Description #3	
Description #4	
Description #5	

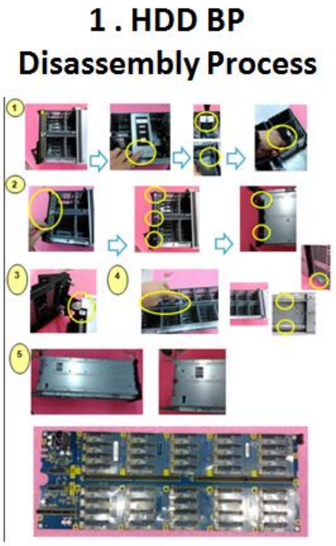
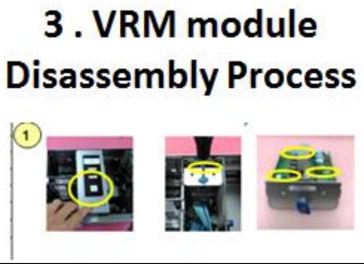
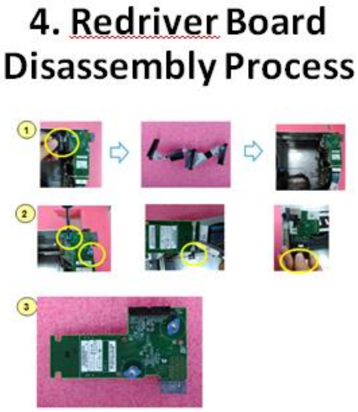
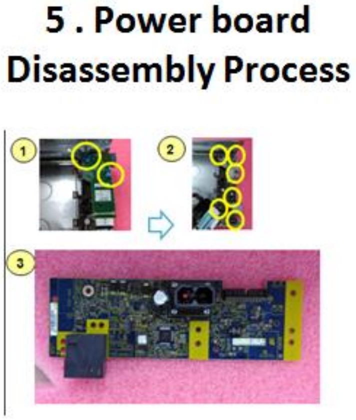
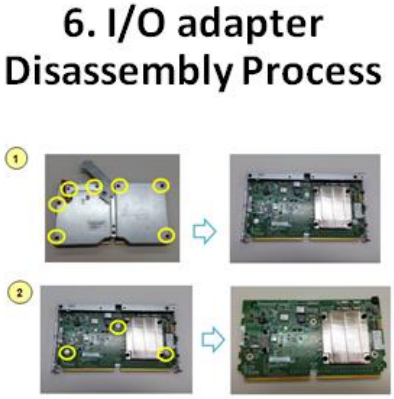
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

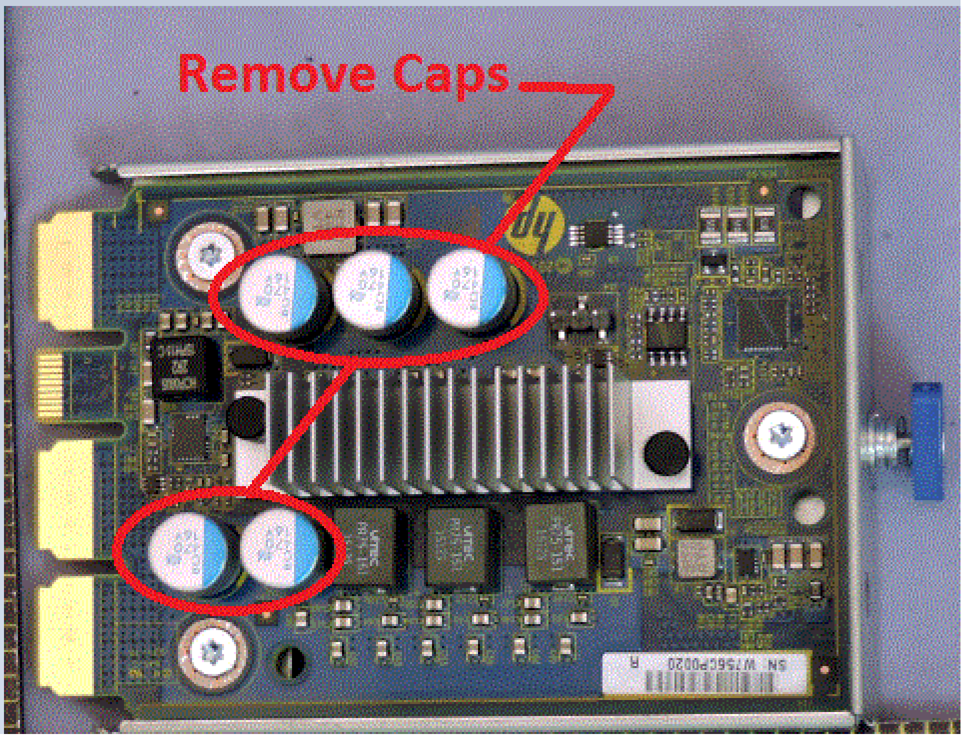
1. Remove HDD BP process
   (1) Remove top cover and pull out the drawer, remove VRM top cover, unlock one thumbscrew on VRM module.
   , Unlock two thumbscrew on cable chain and unplug one power cable and two SAS cables.
   (2)Remove Pinch warning label and unlock 5 screws on Panel's two side.
   (3)Remove LED cable.
   (4)Remove IO module and press three bottom on both side and remove drawer.
   (5) Unlock 4 screw with Philip's head and unlock 20 screw HDD tray.
2. Remove FPLD board process
   Remove LED cable and unlock 2 screws from FPLD board.
3. Remove VRM module process
   (1) Remove VRM top cover
   (2) Unlock one thumbscrew on VRM module.
   (3) Unlock 3 screws on Redriver board
4. Remove Redriver board process
   (1) Remove Manage cable three connector.
   (2) Unlock two thumbscrew, cut off cable tie and remove SAS cable connector.
5. Remove Power board process
   (1) Remove Manage cable,remove redriver board(Up) and metal bar.
   (2) Remove redriver board(Down) and unlock 6 screws from Power board.
6. Remove Power module process
   (1) Unlock 7 screws on I/O adapter top cover.
   (2) Unlock 3 screws on I/O adapter board.

Attachment 1- Remove Electrolytic CAP
Attachment 2- Remove Electrolytic CAP

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1	  
2	  

Attachment 1- Remove Electrolytic Capacitors



Attachment 2- Remove Electrolytic Capacitor